

# **TTEP 2023**

# TEST TECHNOLOGY EDUCATIONAL PROGRAM 2023 Call for Tutorial Proposals (ITC-India, ITC-Asia, ITC, and ATS)

The Tutorials & Education Group (TEG) of the IEEE Computer Society Test Technology Technical Council (TTTC) organizes in 2023 a comprehensive set of Test Technology Tutorials to be held in conjunction with TTTC sponsored technical meetings. The objective of this common call is to invite submissions for tutorial proposals in order to enable selecting the best fitted tutorials for each technical meeting, as part of the annual Test Technology Educational Program (TTEP).

The tutorials accepted by the Program Committee will be included in the Test Technology Educational Program, the intent of which is to serve the test and design professionals offering fundamental education and expert knowledge in state-of-the-art test technology topics.

Participation in TTEP-organized tutorials is *accredited* by Test Technology Technical Council. Each full day tutorial corresponds to four TTEP units (half day tutorial corresponds to two TTEP units). Upon completion of every sixteen units official accreditation in the form of the "*IEEE TTTC Test Technology Certificate*" is presented to the participants.

The TTEP 2023 tutorials program includes (but is not limited to) the following technical meetings:

- International Test Conference India (ITC-India'23)
- International Test Conference Asia (ITC-Asia'23)
- International Test Conference (ITC'23)
- Asian Test Symposium (ATS'23)

TTEP accommodates a wide range of technical areas, from mature test topics of high interest to industrial test engineers to emerging test topics with emphasis on novelty. TTEP is soliciting new and updated tutorial proposals, as well as proposals for Test Clinics, which are particularly geared towards newcomers to the area of test, such as new test engineers and students pursuing graduate studies in test, with an objective of offering a broad yet comprehensive review of basic test topics in an accessible way to the lay audience. The topics of interest for year 2023 TTEP Tutorials include (but are not limited to):

- 3D chiplet testing
- Artificial Intelligence for test
- Automatic test equipment
- Board-level testing
- Built-in self-test (BIST)
- Data analytics
- Defect oriented testing
- Design for testability
- Diagnosis and debug
- Embedded core testing

- Failure analysis techniques
- Functional safety
- High-speed interface testing
- Memory testing
- Mixed-Signal/Analog testing
- Nanometer technology testing
- On-line and In-field testing
- Performance/Delay testing
- Microprocessor testing
- Power issues in testing

- Reliability and automotive testing
- Secure DFT
- System-level testing
- Test economics
- Test resource partitioning
- Test related standards
- Testing machine learning engines
- Verification and validation
- Wafer testing
- Yield optimization and test

**Submissions:** All tutorial proposal submissions to TTEP 2023 are to be made electronically (in PDF format using the TTEP tutorial proposal template provided on both the TTEP main web site and the submission website) through the TTEP submissions website:

http://ttep.tttc-events.org/ttep/submission.html

**Deadline for tutorials proposals:** April 21st, 2023.

**Contact Information:** 

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TTEP central web site: http://ttep.tttc-events.org/ttep/

TTEP web site for submissions: http://ttep.tttc-events.org/ttep/submission.html



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